

ABSTRACT OF THE DISCLOSURE

A package is formed by mounting a plurality of semiconductor chips 6 and 7 on a substrate 1, arranging a heat spreader 13 on a resin surface opposite to a surface where pads 8 for the semiconductor chips are formed, via a curved intermediate plate 11 made of a metal, and filling with resin 14. The curved intermediate plate 11 is formed so as to easily bend in order to compensate the semiconductor chips 6 and 7 for the height difference relative to the heat spreader 13, and has a plurality of bumps 12 on the surface thereof in order to allow contact with the semiconductor chips by multipoint.